

B2884 Board Size (mm)



B2884 BOARD SPECIFICATIONS

1. Board Layers: 4
2. Layer Stack Order:
Layer1 (Artwork_1): Top Signal_2, 0.5 oz, diff. 100 ohms
Layer2 (Artwork_2): Power_1, P1V8, 1 oz
Layer3 (Artwork_3): Power_2, Ground, 1 oz
Layer4 (Artwork_4): Bot Signal_2, 0.5 oz, diff 100 ohms
3. Apply silkscreen on both side:
Artwork_5: Top silkscreen.
Artwork_6: Bot silkscreen.
4. Apply solder mask over bare copper on both side:
Artwork_7: Top solder mask
Artwork_8: Bottom solde mask
5. Material: FR4
6. Board thickness: 0.062'' +/- 0.010.
7. TRACE IMPEDENCE: diff 100 ohms +/- 10% for all signal layers.
8. Emersion gold plating over bare copper
9. All layers mininum trace width/clearence/width = 5/5/5 mils,
10. Trace width can be adusted by matching the impedance requirement by manufacturing
11. All dimensions are in inches unless otherwise noted.

BOARD's DRILL SCHEDULE (Inch)

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
○	.01	160	YES	---
⊞	.015	24	YES	---
⊘	.035	40	YES	---
⊞	.041	1	YES	---
⊖	.048	4	YES	---
⊞	.13779528	4	YES	---

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SCHM# B2883
SPEC# B2884
ASSM# B2885

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
B2884 Specification

SHEET 1 OF 1
DATE 02/01/2017
DRAWN TANG

B- 2884
REV 1.0